

## IN THE CLAIMS

Please cancel claim 20.

Please amend the claims as follows:

1. (Currently amended) A heat spreader, comprising:  
a body formed from heat conductive material; and  
a plurality of standoffs formed on a surface of said body. to reduce bond thickness variation between said heat spreader and an integrated circuit to be coupled to said heat spreader, at least one of said plurality of standoffs top have a flexible sealant material disposed between the at least one of said plurality of standoffs and a substrate coupled to the integrated circuit.
2. (Currently amended) The heat spreader of claim 1, wherein ~~the heat conductive material is further~~ said body is plated with nickel.
3. (Currently amended) The heat spreader of claim 1, wherein ~~the heat conductive material is further~~ said body is coated with heat-conductive organic material.
4. (Currently amended) The heat spreader of claim 1, wherein ~~the body has surface further includes~~ a plurality of mechanical attachment structures bonded to the surface. to couple to a package substrate with a sealant.

5. (Currently amended) A heat spreader, comprising:  
a body formed from heat conductive material; and  
a ~~non-contiguous-wall structure formed around the~~ about a periphery of said  
body- to couple to a package substrate through a flexible material.
6. (Currently amended) The heat spreader of claim 5, wherein ~~the heat~~  
~~conductive material is further~~ said body is plated with nickel.
7. (Currently amended) The heat spreader of claim 5 wherein ~~the heat~~  
~~conductive material~~ said body is coated with a heat-conductive organic material.
8. (Currently amended) ~~A heat spreader~~ An apparatus, comprising:  
a heat spreader comprising a body formed from heat conductive material;  
and a wall structure; and  
a flexible material coupled to the wall structure and to couple to a package  
substrate. formed around the periphery of said body; and  
a plurality of standoffs formed on the inside surface of said body.
9. (Currently amended) The ~~heat spreader~~ apparatus of claim 8, wherein the  
~~wall structure is non-contiguous.~~ flexible material comprises polymeric sealant  
material.
10. (Currently amended) The ~~heat spreader~~ apparatus of claim ~~98~~, wherein the  
~~heat conductive material is further~~ said body is plated with nickel.

11. (Currently amended) The heat spreader apparatus of claim ~~98~~, wherein the ~~heat-conductive material~~ said body is coated with a heat-conductive organic material.

12. (Original) A heat spreader, comprising:  
a body formed from heat-conductive material; and  
a pedestal formed on said body.

13. (Original) The heat spreader of claim 12, wherein the heat conductive material is further plated with nickel.

14. (Original) The heat spreader of claim 12, wherein the heat conductive material is coated with heat-conductive organic material.

15. (Original) A heat spreader, comprising:  
a body formed from heat-conductive material;  
a wall structure on the periphery of said body; and  
a pedestal formed on said body.

16. (Original) The heat spreader of claim 15, wherein the heat conductive material is further plated with nickel.

17. (Original) The heat spreader of claim 15, wherein the heat conductive material is coated with a heat-conductive organic material.

18. (Currently amended) A semiconductor package, comprising:  
a substrate having a top surface;  
at least one semiconductor device attached to said top surface of said substrate; and  
a cover secured to said substrate through a flexible sealant material and  
creating a space ~~therebetween,~~ said substrate and said cover, said semiconductor device residing within said space, and secured to said substrate and said cover  
~~having a flat top surface with standoffs attached thereon and an external bottom surface; and~~ said cover further comprised of a heat-conductive material.

19. (Original) The semiconductor package of claim 18, wherein the cover is a heat spreader.

20. (Cancelled)

21. (Original) The semiconductor package of claim 19, wherein the cover has mechanical attachment structures bonded to the surface.

22. (Currently amended) The semiconductor package of claim 18<sup>9</sup>, wherein the heat spreader ~~is attached to the substrate using~~ has a wall structure; about a  
periphery thereof to couple to said substrate.

22<sup>3</sup>. (Currently amended) The semiconductor package of claim 18, wherein the flat top surface has a pedestal.